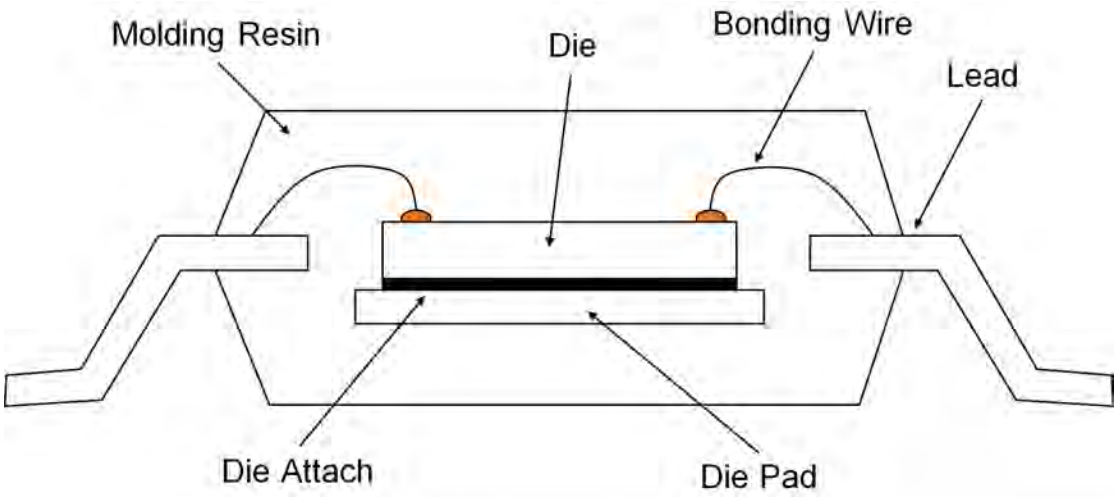
Package Information : SOP-J14

1. Package Information

Package Name	SOP-J14
Type	SOP
Pin Count	14
Package Weight [g]	0.12
Lead Finish	Pure Tin
MSL	Level1

2. Package Structure



3. Packing Specification

3.1 Packing form, Quantity, PIN1 Orientation

Packing Form		Tape&Reel
Packing Quantity	[pcs]	2,500
PIN 1 Orientation		E2

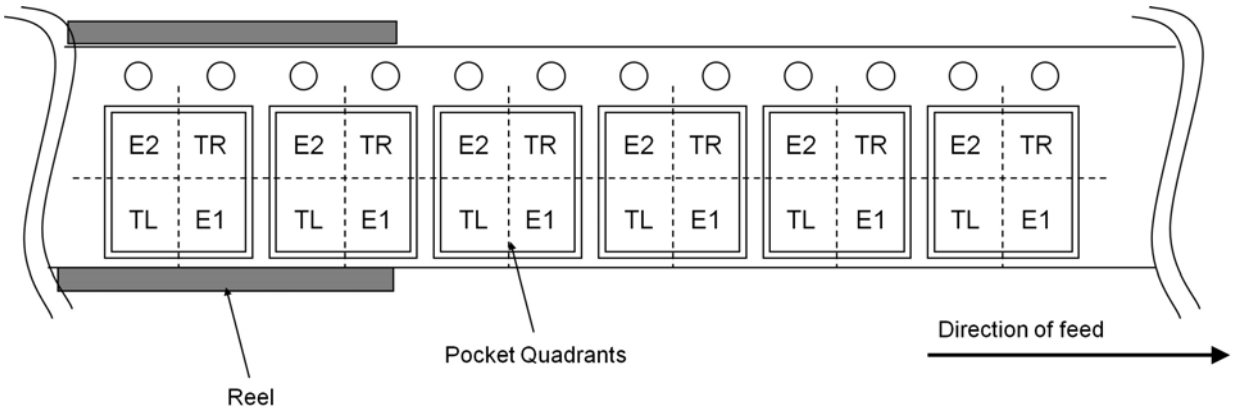


Fig.1 Quadrant Assignments for PIN 1 Orientation in Tape

E2 : PIN1 is placed to the top left corner. TR : PIN1 is placed to the top right corner.

TL : PIN1 is placed to the lower left. E1 : PIN1 is placed to the lower right.

Fig.1 PIN 1 Orientation in Tape

3.2 Use material

Item	Material
Embossed carrier tape	PS
Cover tape	PET+PE
Reel	PS
Air cap	PE
Unit box	Cardboard
Shipping box	Cardboard

3.3 Leader specification

No component pockets are 320 mm or more.

3.4 Trailer specification

No component pockets are 80 mm or more. Tape is free from reel.

3.5 Peelback strength

Cover tape peelback strength is 0.2 N to 0.7 N.

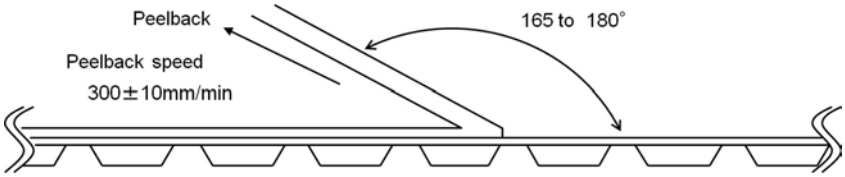


Fig. 2 Test method

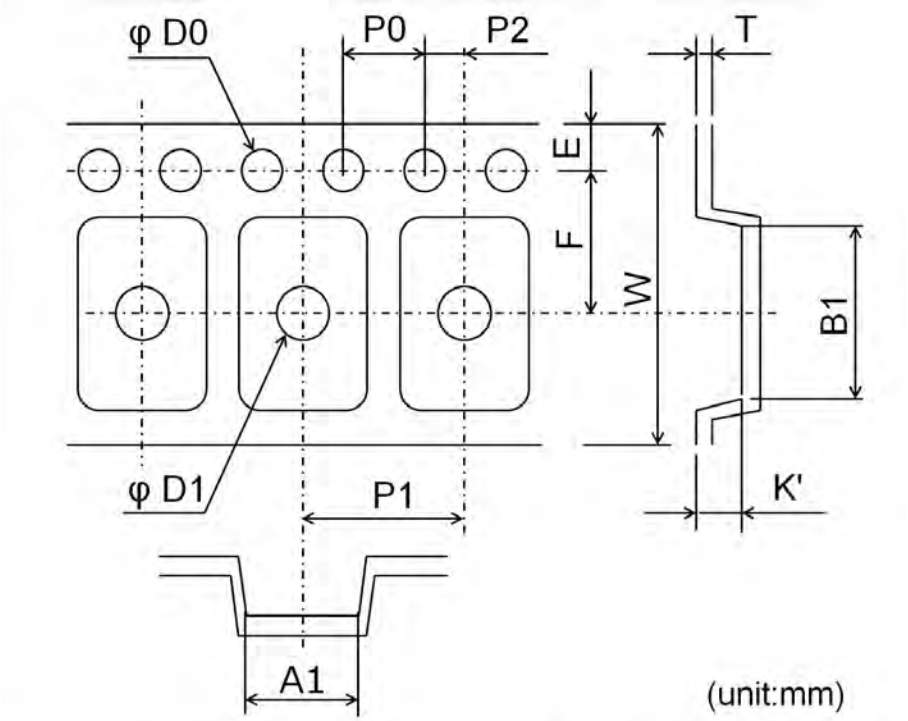
3.6 Missing Ics

(1) No consecutive dropouts.

(2) A maximun 0.1 % of specified number of products in each packing may be missing.

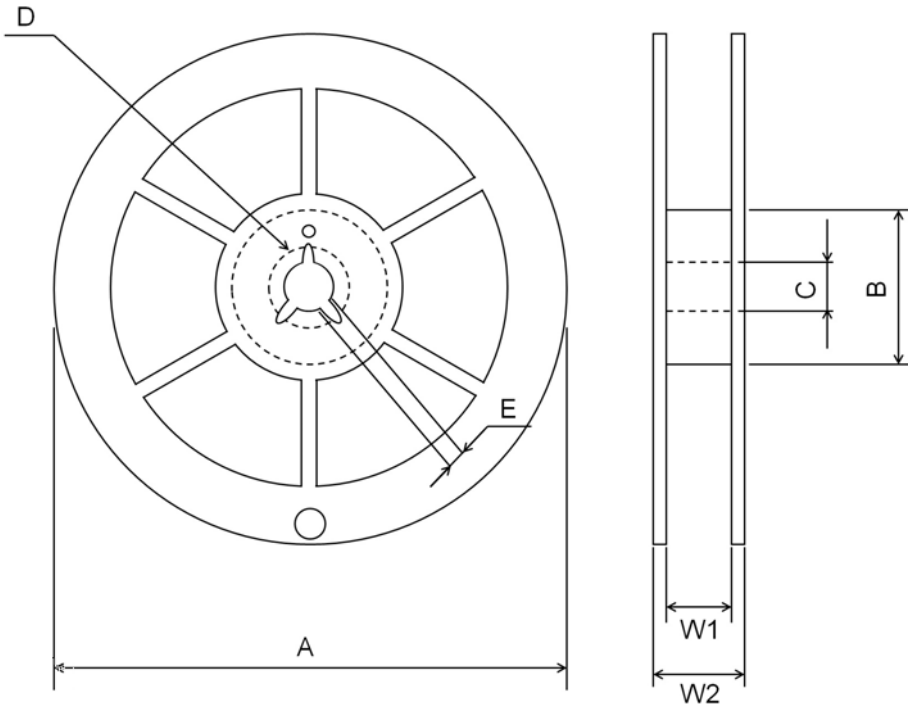
3.7 Tape and Reel Specification

3.7.1 Tape Dimension



	Tape Dimension	Tape Tolerance
A1	6.55	±0.1
B1	9.15	±0.1
D0	φ1.5	+0.1/-0
D1	φ1.5	MIN
E	1.75	±0.1
F	7.50	±0.1
K'	1.80	±0.1
P0	4.00	±0.1
P1	8.00	±0.1
P2	2.00	±0.1
T	0.30	-
W	16.0	±0.3

3.7.2 Reel Dimension

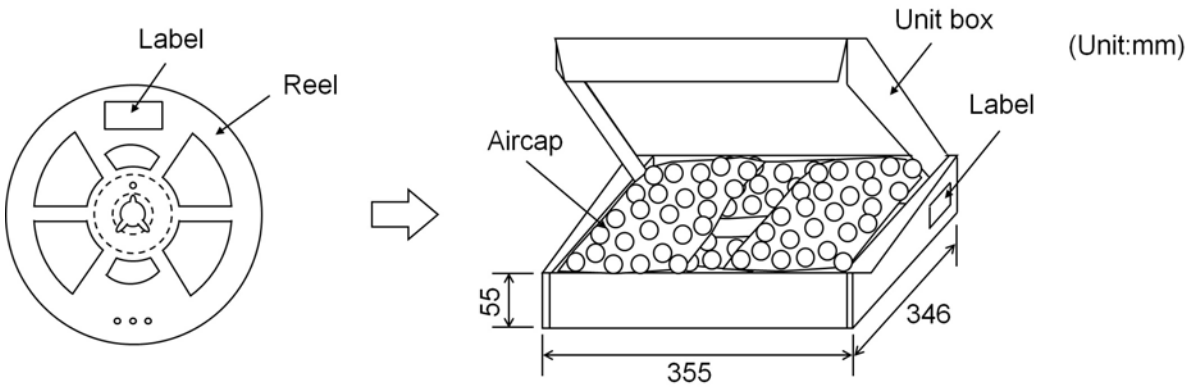


(unit:mm)

	Reel Dimension	Reel Tolerance
A	330	±2.0
B	80	±1.0
C	13	±0.2
D	21	±0.8
E	2	±0.5
W1	17.5	±1.0
W2	21.5	±1.0

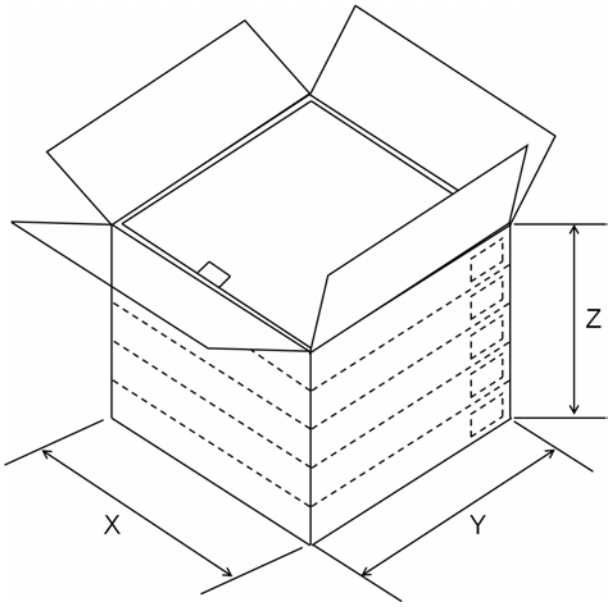
3.8 Packing Method

1 reel(s) or less per unit box



3.9 Packing Style

5 unit boxes or less per shipping box



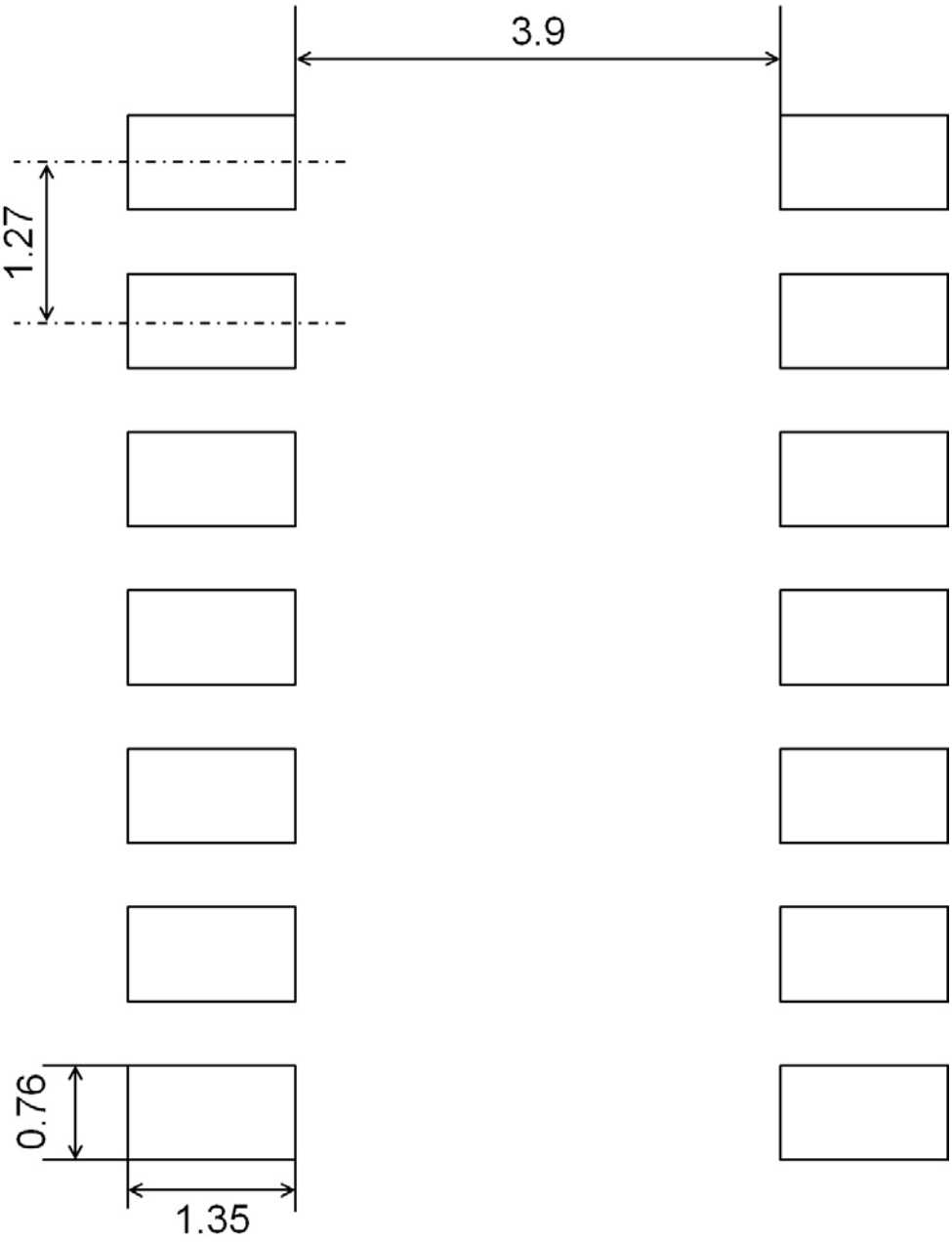
(unit:mm)

Shipping Box Dimension	
X	372
Y	368
Z	305

3.10 Label Specification

Label Example

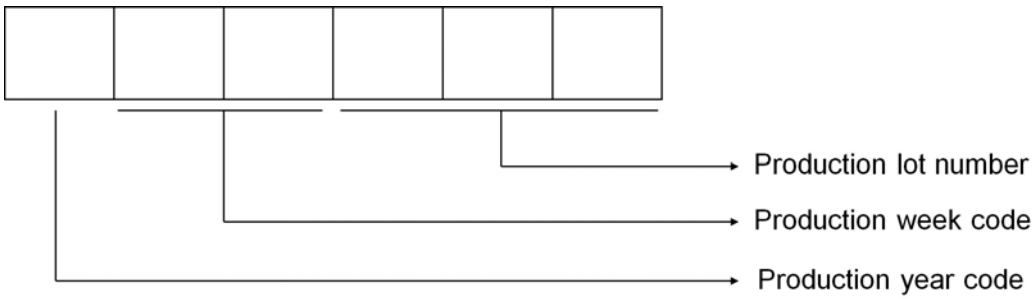
4. Footprint dimensions



(unit:mm)

In actual design, please optimize in accordance with the situation of your board design and soldering condition.

5. Marking Specification



6. Storage conditions

6.1 Storage environment

Recommended storage conditions

	Min.	Max.	Unit
Temperature	5	30	°C
Humidity	-	85	% RH

6.2 Storage period (Start to count since delivery date)

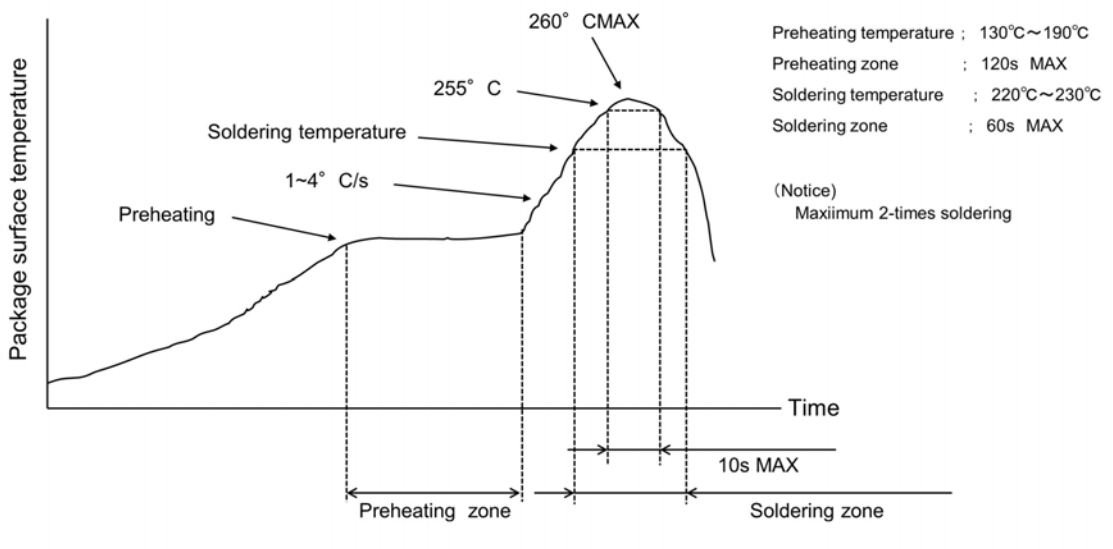
	Min.	Max.	Unit
Storage period	-	1	year

6.3 Drying process

Dryprocess is not required before solder mounting.

7. Soldering conditions

7.1 Recommended temperature profile for reflow



7.2 Recommended condition for wave soldering

Preheating temperature	:	120 °C to 150 °C
Preheating time	:	60 s MAX
Soldering temperature	:	260 °C ± 3 °C
Soldering time	:	12 s MAX

Notes for wave soldering

(1)Soldering time is provided for total soldering time in case of dual wave soldering.

(2) Do not use other soldering methods with wave soldering.

(3) Recommend to clean the board to eliminate flux, solder waste,
and other impurities for reliability, after soldering.

(4) Optimize soldering condition to prevent solder bridging.

7.3 Recommended condition for solder iron

Solder iron temperature	:	380 °C or less
Mounting time	:	4 s or less

Notes for solder iron

(1)Solder mounting time is the time per 1 lead

Notes

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7) The Products specified in this document are not designed to be radiation tolerant.

8) For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e. cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.

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